

## Applications

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply
- High Speed Power Switching

| $V_{DSS}$ | $R_{DS(on)}$ typ. | $I_D$ |
|-----------|-------------------|-------|
| 500V      | 0.070Ω            | 40A   |

## Benefits

- Low Gate Charge  $Q_g$  results in Simple Drive Requirement
- Improved Gate, Avalanche and Dynamic  $dv/dt$  Ruggedness
- Fully Characterized Capacitance and Avalanche Voltage and Current



## Absolute Maximum Ratings

|                                   | Parameter                                                   | Max.         | Units |
|-----------------------------------|-------------------------------------------------------------|--------------|-------|
| $I_D$ @ $T_C = 25^\circ\text{C}$  | Continuous Drain Current, $V_{GS}$ @ 10V                    | 40           | A     |
| $I_D$ @ $T_C = 100^\circ\text{C}$ | Continuous Drain Current, $V_{GS}$ @ 10V                    | 25           |       |
| $I_{DM}$                          | Pulsed Drain Current ①                                      | 160          |       |
| $P_D$ @ $T_C = 25^\circ\text{C}$  | Power Dissipation                                           | 310          | W     |
|                                   | Linear Derating Factor                                      | 2.5          | W/°C  |
| $V_{GS}$                          | Gate-to-Source Voltage                                      | ± 20         | V     |
| $dv/dt$                           | Peak Diode Recovery $dv/dt$ ③                               | 5.0          | V/ns  |
| $T_J$<br>$T_{STG}$                | Operating Junction and<br>Storage Temperature Range         | -55 to + 150 | °C    |
|                                   | Soldering Temperature, for 10 seconds<br>(1.6mm from case ) | 300          |       |
|                                   | Recommended clip force                                      | 20           |       |

## Avalanche Characteristics

| Symbol   | Parameter                      | Typ. | Max. | Units |
|----------|--------------------------------|------|------|-------|
| $E_{AS}$ | Single Pulse Avalanche Energy② | —    | 480  | mJ    |
| $I_{AR}$ | Avalanche Current①             | —    | 34   | A     |
| $E_{AR}$ | Repetitive Avalanche Energy①   | —    | 31   | mJ    |

## Thermal Resistance

| Symbol          | Parameter                           | Typ. | Max. | Units |
|-----------------|-------------------------------------|------|------|-------|
| $R_{\theta JC}$ | Junction-to-Case                    | —    | 0.40 | °C/W  |
| $R_{\theta CS}$ | Case-to-Sink, Flat, Greased Surface | 0.50 | —    |       |
| $R_{\theta JA}$ | Junction-to-Ambient                 | —    | 58   |       |

# IRFBA34N50C

PROVISIONAL

International  
IR Rectifier

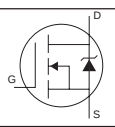
## Static @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

| Symbol                          | Parameter                            | Min. | Typ.  | Max.  | Units    | Conditions                                            |
|---------------------------------|--------------------------------------|------|-------|-------|----------|-------------------------------------------------------|
| $V_{(BR)DSS}$                   | Drain-to-Source Breakdown Voltage    | 500  | —     | —     | V        | $V_{GS} = 0V, I_D = 250\mu A$                         |
| $\Delta V_{(BR)DSS}/\Delta T_J$ | Breakdown Voltage Temp. Coefficient  | —    | 0.68  | —     | V/°C     | Reference to $25^\circ\text{C}, I_D = 1mA$ ⑥          |
| $R_{DS(on)}$                    | Static Drain-to-Source On-Resistance | —    | 0.070 | 0.075 | $\Omega$ | $V_{GS} = 10V, I_D = 24A$ ④                           |
| $V_{GS(th)}$                    | Gate Threshold Voltage               | 3.5  | —     | 5.5   | V        | $V_{DS} = V_{GS}, I_D = 250\mu A$                     |
| $I_{DSS}$                       | Drain-to-Source Leakage Current      | —    | —     | 25    | $\mu A$  | $V_{DS} = 500V, V_{GS} = 0V$                          |
|                                 |                                      | —    | —     | 250   |          | $V_{DS} = 400V, V_{GS} = 0V, T_J = 125^\circ\text{C}$ |
| $I_{GSS}$                       | Gate-to-Source Forward Leakage       | —    | —     | 100   | nA       | $V_{GS} = 20V$                                        |
|                                 | Gate-to-Source Reverse Leakage       | —    | —     | -100  |          | $V_{GS} = -20V$                                       |

## Dynamic @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

| Symbol                 | Parameter                       | Min. | Typ.  | Max. | Units | Conditions                                            |
|------------------------|---------------------------------|------|-------|------|-------|-------------------------------------------------------|
| $g_{fs}$               | Forward Transconductance        | 20   | —     | —    | S     | $V_{DS} = 50V, I_D = 20A$                             |
| $Q_g$                  | Total Gate Charge               | —    | 190   | —    | nC    | $I_D = 20A$                                           |
| $Q_{gs}$               | Gate-to-Source Charge           | —    | 45    | —    |       | $V_{DS} = 400V$                                       |
| $Q_{gd}$               | Gate-to-Drain ("Miller") Charge | —    | 90    | —    |       | $V_{GS} = 10V, \text{ ④}$                             |
| $t_{d(on)}$            | Turn-On Delay Time              | —    | 23    | —    | ns    | $V_{DD} = 250V$                                       |
| $t_r$                  | Rise Time                       | —    | 29    | —    |       | $I_D = 20A$                                           |
| $t_{d(off)}$           | Turn-Off Delay Time             | —    | 55    | —    |       | $R_G = 1.3\Omega$                                     |
| $t_f$                  | Fall Time                       | —    | 6.3   | —    |       | $V_{GS} = 10V, \text{ ④}$                             |
| $C_{iss}$              | Input Capacitance               | —    | 6330  | —    | pF    | $V_{GS} = 0V$                                         |
| $C_{oss}$              | Output Capacitance              | —    | 3600  | —    |       | $V_{DS} = 25V$                                        |
| $C_{rss}$              | Reverse Transfer Capacitance    | —    | 140   | —    |       | $f = 1.0MHz$                                          |
| $C_{oss}$              | Output Capacitance              | —    | 15150 | —    |       | $V_{GS} = 0V, V_{DS} = 1.0V, f = 1.0MHz$              |
| $C_{oss}$              | Output Capacitance              | —    | 140   | —    |       | $V_{GS} = 0V, V_{DS} = 400V, f = 1.0MHz$              |
| $C_{oss \text{ eff.}}$ | Effective Output Capacitance    | —    | 460   | —    |       | $V_{GS} = 0V, V_{DS} = 0V \text{ to } 400V \text{ ⑤}$ |

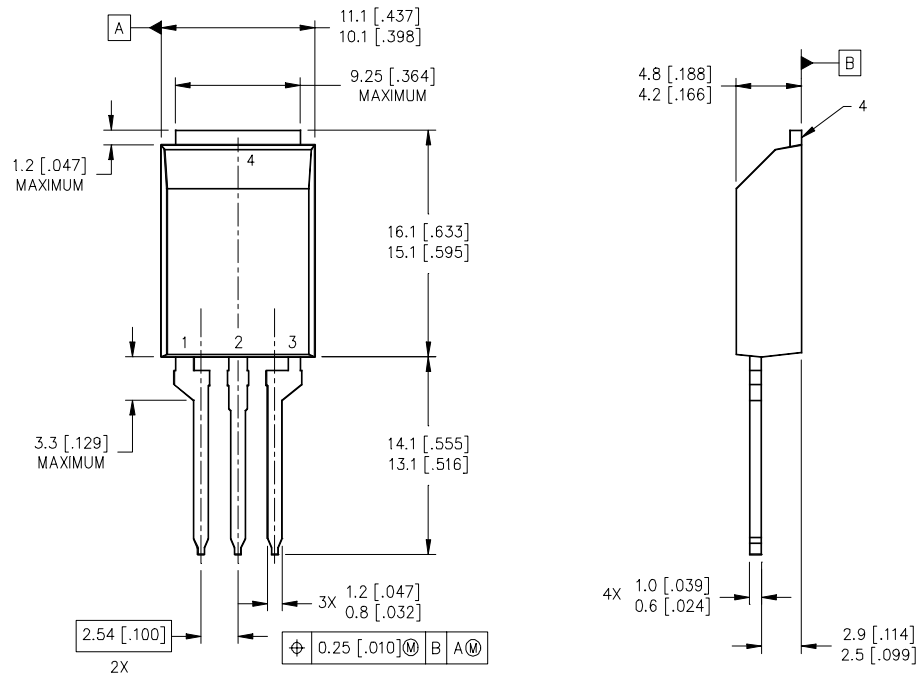
## Diode Characteristics

| Symbol   | Parameter                              | Min.                                                                        | Typ. | Max. | Units   | Conditions                                                                                                                                           |
|----------|----------------------------------------|-----------------------------------------------------------------------------|------|------|---------|------------------------------------------------------------------------------------------------------------------------------------------------------|
| $I_S$    | Continuous Source Current (Body Diode) | —                                                                           | —    | 40   | A       | MOSFET symbol showing the integral reverse p-n junction diode.  |
| $I_{SM}$ | Pulsed Source Current (Body Diode) ①   | —                                                                           | —    | 160  |         |                                                                                                                                                      |
| $V_{SD}$ | Diode Forward Voltage                  | —                                                                           | —    | 1.5  | V       | $T_J = 25^\circ\text{C}, I_S = 24A, V_{GS} = 0V$ ④                                                                                                   |
| $t_{rr}$ | Reverse Recovery Time                  | —                                                                           | 510  | 770  | ns      | $T_J = 125^\circ\text{C}, I_F = 20A$                                                                                                                 |
| $Q_{rr}$ | Reverse Recovery Charge                | —                                                                           | 11   | 17   | $\mu C$ | $di/dt = 100A/\mu s$ ④                                                                                                                               |
| $t_{on}$ | Forward Turn-On Time                   | Intrinsic turn-on time is negligible (turn-on is dominated by $L_S + L_D$ ) |      |      |         |                                                                                                                                                      |

### Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Starting  $T_J = 25^\circ\text{C}$ ,  $L = 0.83mH$ ,  $R_G = 25\Omega$ ,  $I_{AS} = 34A$ ,
- ③  $I_{SD} \leq 20A$ ,  $di/dt \leq 42A/\mu s$ ,  $V_{DD} \leq V_{(BR)DSS}$ ,  $T_J \leq 150^\circ\text{C}$
- ④ Pulse width  $\leq 300\mu s$ ; duty cycle  $\leq 2\%$ .

## Super-220™ Package Outline



### NOTES:

1. DIMENSIONING & TOLERANCING PER ASME Y14.5M-1994.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
4. OUTLINE CONFORMS TO JEDEC OUTLINE TO-273AA.

### LEAD ASSIGNMENTS

| MOSFET     | IGBT          |
|------------|---------------|
| 1 - GATE   | 1 - GATE      |
| 2 - DRAIN  | 2 - COLLECTOR |
| 3 - SOURCE | 3 - EMITTER   |
| 4 - DRAIN  | 4 - COLLECTOR |